

SN74ALS533A, SN74AS533A
OCTAL D-TYPE TRANSPARENT LATCHES
WITH 3-STATE OUTPUTS

SDAS270 - DECEMBER 1994

- Eight Latches in a Single Package
- 3-State Bus-Driving Inverting Outputs
- Full Parallel Access for Loading
- Buffered Control Inputs
- pnp Inputs Reduce dc Loading on Data Lines
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (N) 300-mil DIPs

description

These 8-bit D-type transparent latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

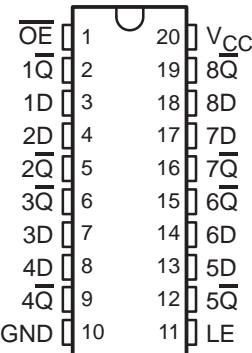
While latch-enable (LE) input is high, the \bar{Q} outputs follow the complements of the data (D) inputs. When LE is taken low, the \bar{Q} outputs are latched at the inverses of the levels set up at the D inputs. The SN74ALS533A and SN74AS533A are functionally equivalent to the SN74ALS373A and SN74AS373, except for having inverted outputs.

A buffered output-enable (\bar{OE}) input places the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

\bar{OE} does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are off.

The SN74ALS533A and SN74AS533A are characterized for operation from 0°C to 70°C.

DW OR N PACKAGE
(TOP VIEW)



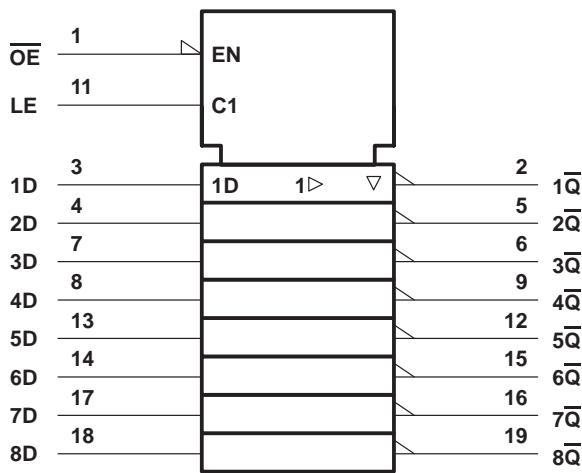
FUNCTION TABLE
(each latch)

INPUTS			OUTPUT
\bar{OE}	LE	D	\bar{Q}
L	H	H	L
L	H	L	H
L	L	X	\bar{Q}_0
H	X	X	Z

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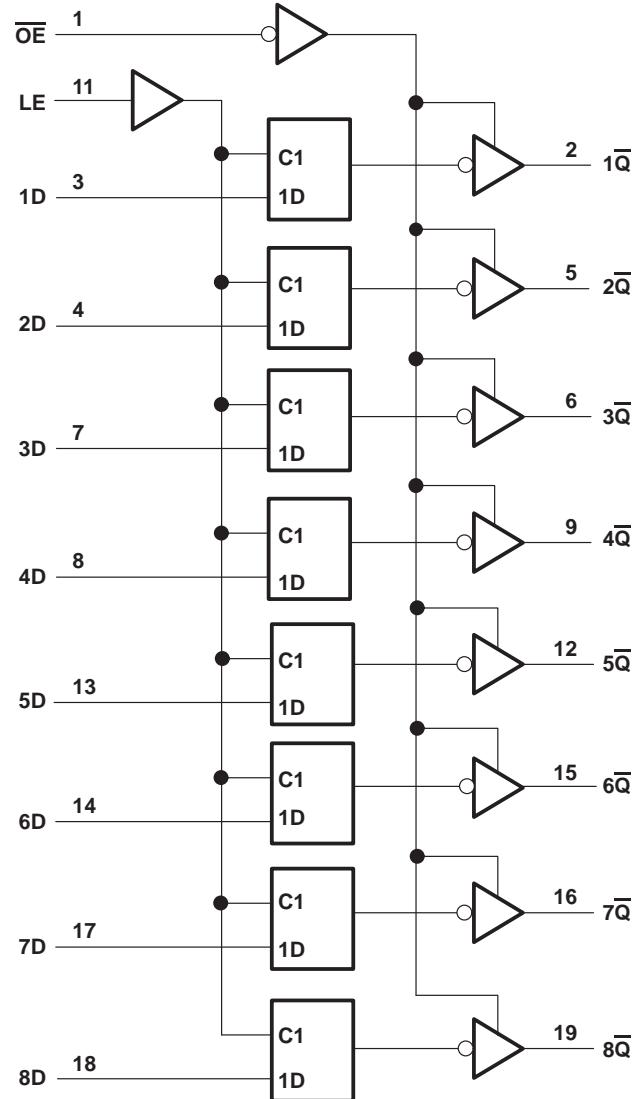
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T_A : SN74ALS533A	0°C to 70°C
Storage temperature range	-65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

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recommended operating conditions

		SN74ALS533A			UNIT
		MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			V
V _{IL}	Low-level input voltage			0.8	V
I _{OH}	High-level output current			-2.6	mA
I _{OL}	Low-level output current			24	mA
t _w	Pulse duration, LE high	15			ns
t _{su}	Setup time, data before LE↓	15			ns
t _h	Hold time, data after LE↓	7			ns
T _A	Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN74ALS533A			UNIT
		MIN	TYPT [†]	MAX	
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA			-1.5	V
V _{OH}	V _{CC} = 4.5 V to 5.5 V, I _{OH} = -0.4 mA	V _{CC} – 2			V
	V _{CC} = 4.5 V, I _{OH} = -2.6 mA	2.4	3.2		
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 12 mA	0.25	0.4	V
		I _{OL} = 24 mA	0.35	0.5	
I _{OZH}	V _{CC} = 5.5 V, V _O = 2.7 V			20	µA
I _{OZL}	V _{CC} = 5.5 V, V _O = 0.4 V			-20	µA
I _I	V _{CC} = 5.5 V, V _I = 7 V			0.1	mA
I _{IH}	V _{CC} = 5.5 V, V _I = 2.7 V			20	µA
I _{IL}	V _{CC} = 5.5 V, V _I = 0.4 V			-0.1	mA
I _{O‡}	V _{CC} = 5.5 V, V _O = 2.25 V	-30	-112		mA
I _{CC}	V _{CC} = 5.5 V	Outputs high	10	17	mA
		Outputs low	17	26	
		Outputs disabled	18.5	28	

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

**SN74ALS533A, SN74AS533A
OCTAL D-TYPE TRANSPARENT LATCHES
WITH 3-STATE OUTPUTS**

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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5\text{ V to }5.5\text{ V},$ $C_L = 50\text{ pF},$ $R1 = 500\text{ }\Omega,$ $R2 = 500\text{ }\Omega,$ $T_A = \text{MIN to MAX}^\dagger$	UNIT	
			SN74ALS533A		
			MIN	MAX	
t_{PLH}	D	\bar{Q}	4	19	ns
t_{PHL}			4	13	
t_{PLH}	LE	Any \bar{Q}	5	23	ns
t_{PHL}			4	18	
t_{PZH}	\overline{OE}	Any \bar{Q}	1	17	ns
t_{PZL}			4	18	
t_{PHZ}	\overline{OE}	Any \bar{Q}	2	10	ns
t_{PLZ}			2	16	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T_A : SN74AS533A	0°C to 70°C
Storage temperature range	-65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN74AS533A			UNIT
		MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
I_{OH}	High-level output current			-15	mA
I_{OL}	Low-level output current			48	mA
t_w	Pulse duration, LE high	2			ns
t_{su}	Setup time, data before $LE \downarrow$	2			ns
t_h	Hold time, data after $LE \downarrow$	3			ns
T_A	Operating free-air temperature	0		70	°C

SN74ALS533A, SN74AS533A
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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN74AS533A			UNIT
		MIN	TYP†	MAX	
V_{IK}	$V_{CC} = 4.5 \text{ V}$, $I_I = -18 \text{ mA}$			-1.5	V
V_{OH}	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$, $I_{OH} = -2 \text{ mA}$	$V_{CC} - 2$			V
	$V_{CC} = 4.5 \text{ V}$, $I_{OH} = -15 \text{ mA}$	2.4	3.3		
V_{OL}	$V_{CC} = 4.5 \text{ V}$, $I_{OL} = 48 \text{ mA}$	0.34	0.5		V
I_{OZH}	$V_{CC} = 5.5 \text{ V}$, $V_O = 2.7 \text{ V}$			50	μA
I_{OZL}	$V_{CC} = 5.5 \text{ V}$, $V_O = 0.4 \text{ V}$			-50	μA
I_I	$V_{CC} = 5.5 \text{ V}$, $V_I = 7 \text{ V}$			0.1	mA
I_{IH}	$V_{CC} = 5.5 \text{ V}$, $V_I = 2.7 \text{ V}$			20	μA
I_{IL}	$V_{CC} = 5.5 \text{ V}$, $V_I = 0.4 \text{ V}$	-0.02	-0.5		mA
$I_O‡$	$V_{CC} = 5.5 \text{ V}$, $V_O = 2.25 \text{ V}$	-30	-112		mA
I_{CC}	$V_{CC} = 5.5 \text{ V}$	Outputs high	62	100	mA
		Outputs low	64	100	
		Outputs disabled	71	110	

† All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$.

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

switching characteristics (see Figure 1)

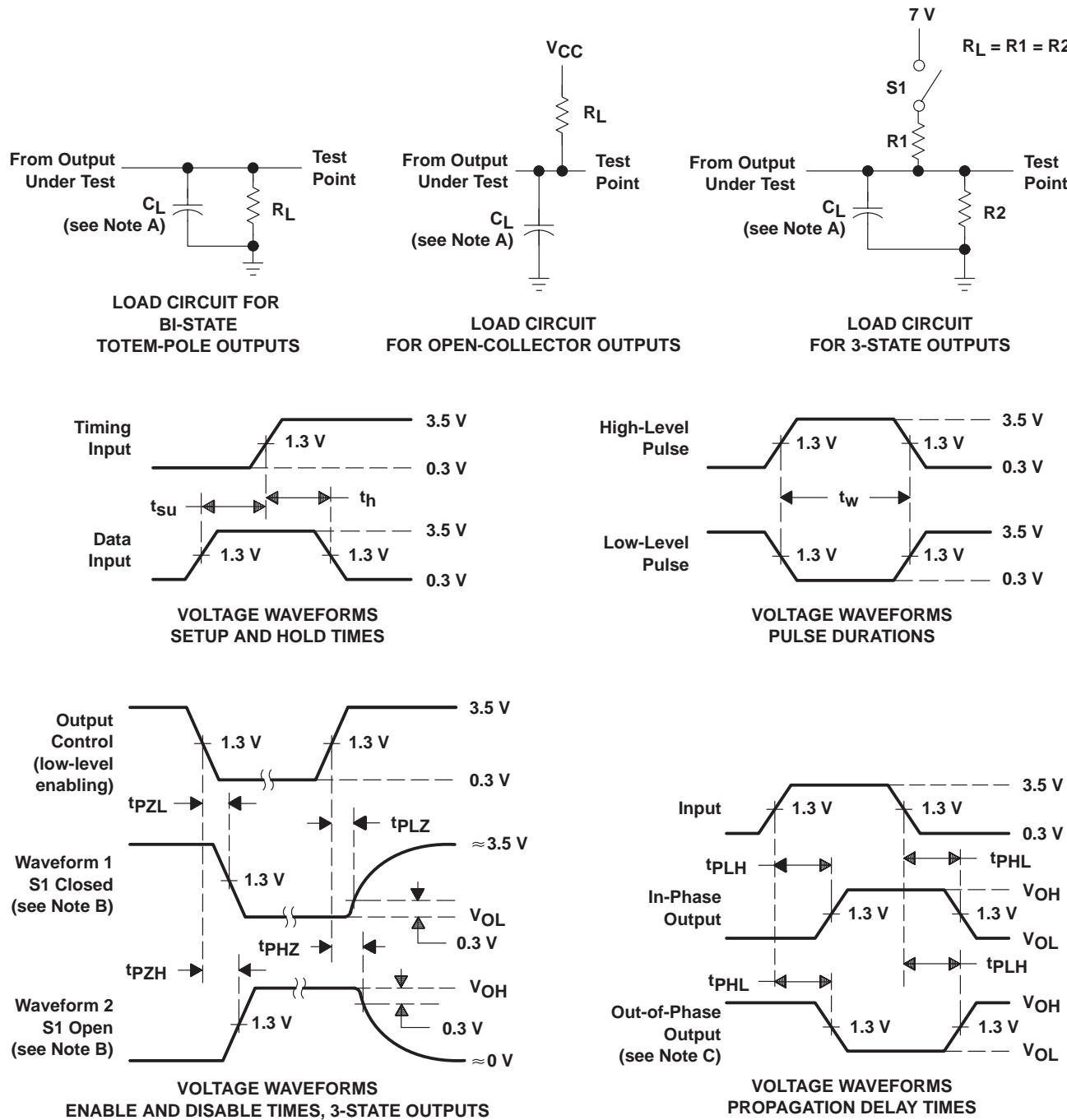
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$, $C_L = 50 \text{ pF}$, $R1 = 500 \Omega$, $R2 = 500 \Omega$, $T_A = \text{MIN to MAX}^\S$	UNIT	
			SN74AS533A		
			MIN	MAX	
t_{PLH}	D	\bar{Q}	4	7.5	ns
t_{PHL}			4	7	
t_{PLH}	LE	Any \bar{Q}	5	9	ns
t_{PHL}			4	8	
t_{PZH}	\bar{OE}	Any \bar{Q}	2	6.5	ns
t_{PZL}			4	9.5	
t_{PHZ}	\bar{OE}	Any \bar{Q}	2	6.5	ns
t_{PLZ}			3	7	

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

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**PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES**



NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 D. All input pulses have the following characteristics: $PRR \leq 1 \text{ MHz}$, $t_r = t_f = 2 \text{ ns}$, duty cycle = 50%.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74ALS533ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS533A	Samples
SN74ALS533ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS533A	Samples
SN74ALS533ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS533A	Samples
SN74ALS533ADWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70	ALS533A	
SN74ALS533ADWRE4	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS533ADWRG4	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS533AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS533AN	Samples
SN74ALS533ANE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS533AN	Samples
SN74ALS533ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS533A	Samples
SN74ALS533ANSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS533A	Samples
SN74ALS533ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS533A	Samples
SN74AS533ADW	NRND	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS533A	
SN74AS533ADWE4	NRND	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS533A	
SN74AS533ADWG4	NRND	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS533A	
SN74AS533AN	NRND	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS533AN	
SN74AS533ANE4	NRND	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS533AN	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

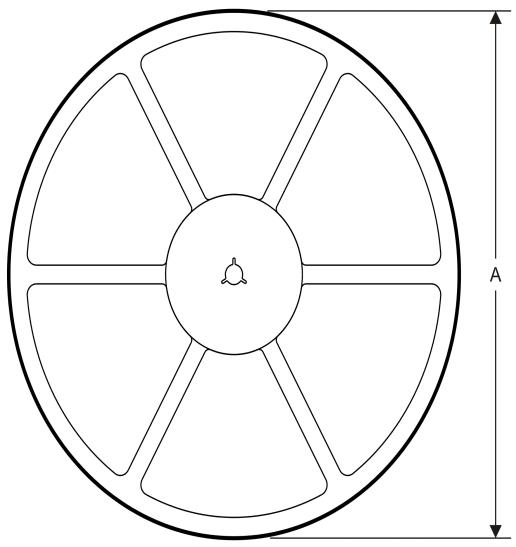
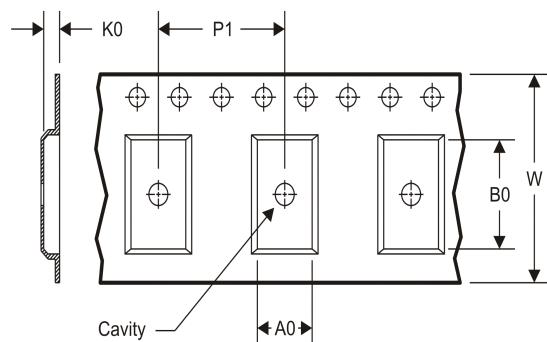
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

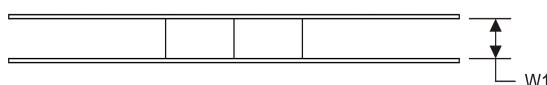
⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.

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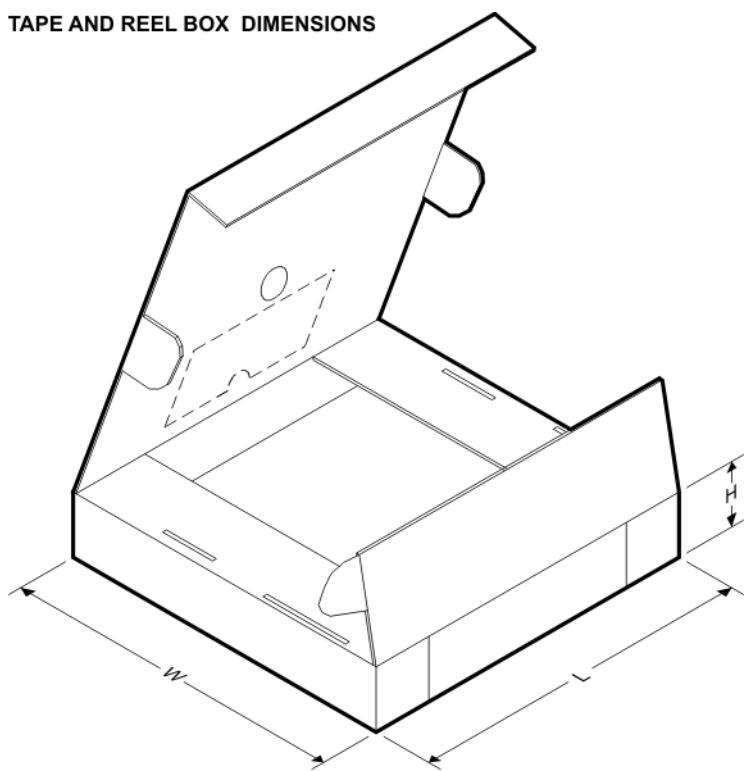
TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers


TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS533ANSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

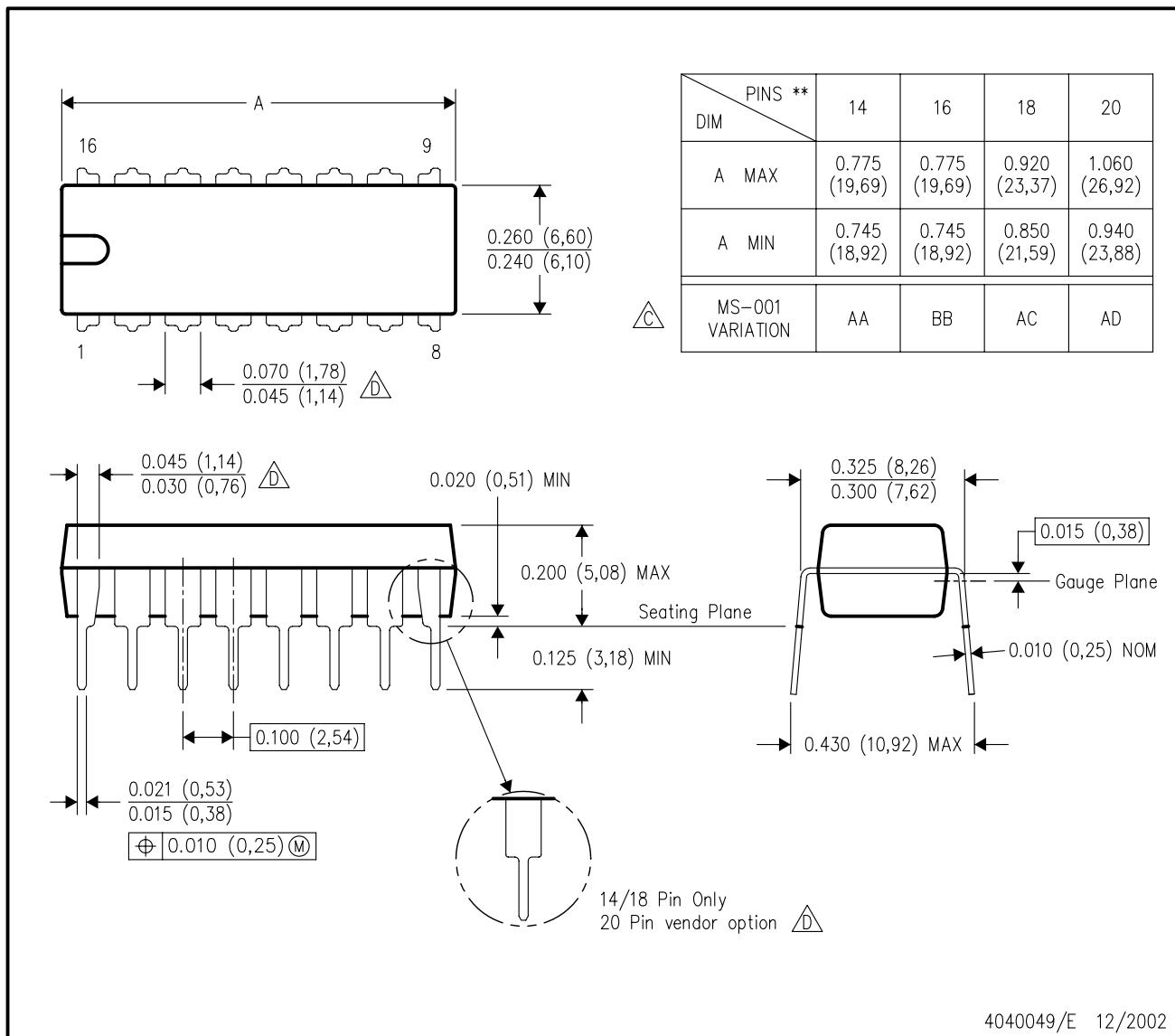
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS533ANSR	SO	NS	20	2000	367.0	367.0	45.0

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



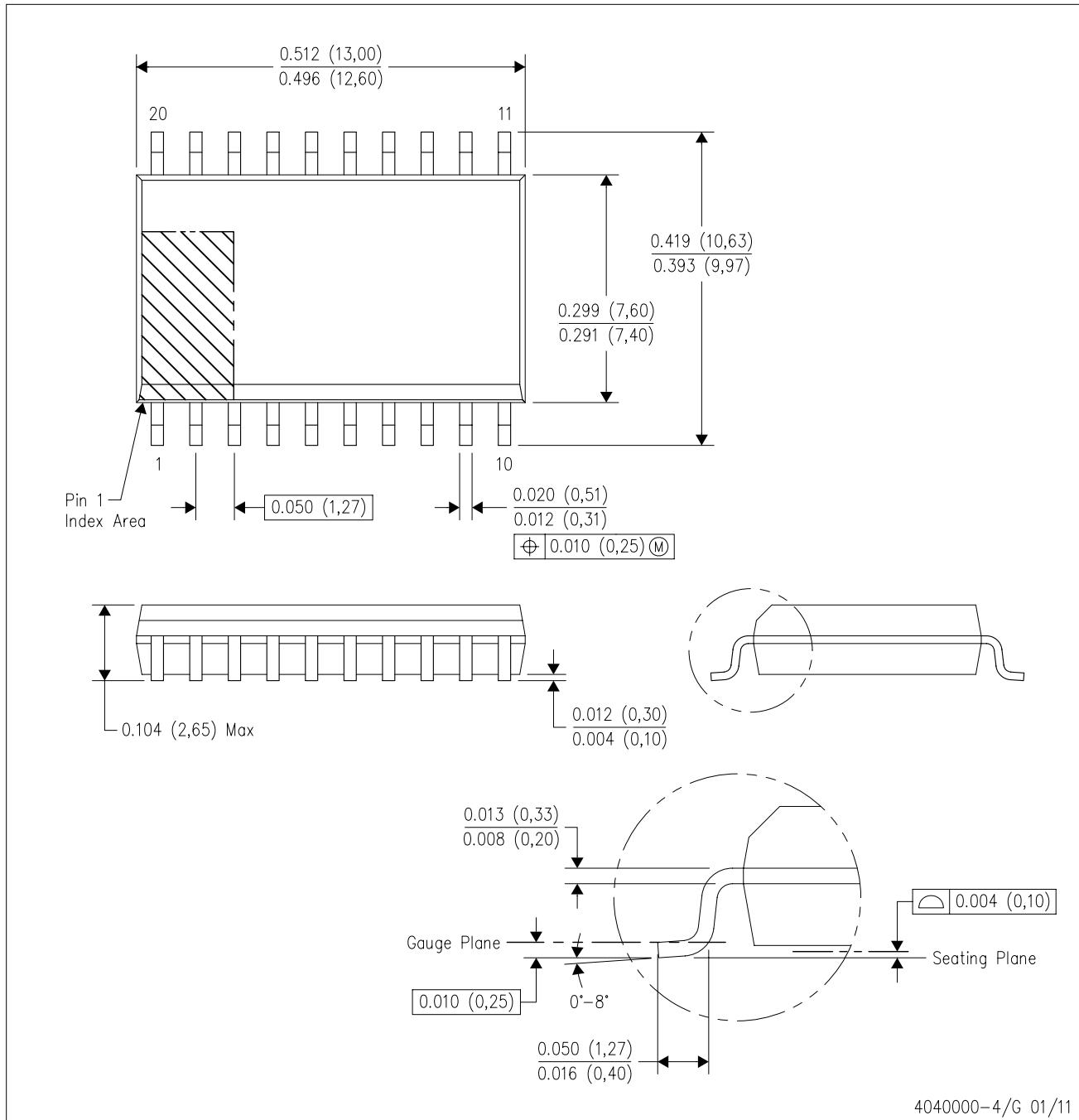
NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.

△ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

△ The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

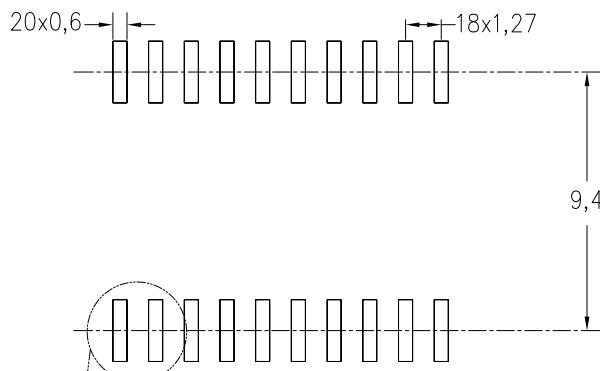
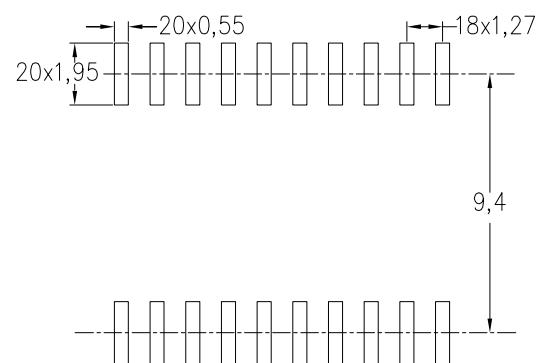


NOTES:

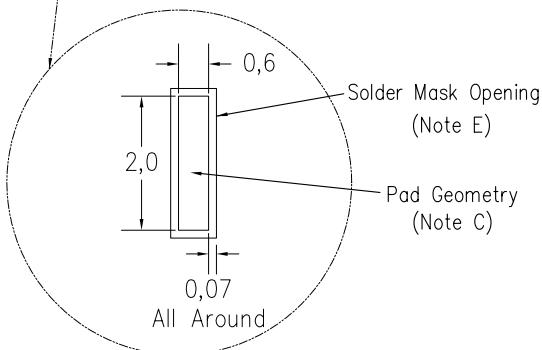
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0.15).
- Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)Stencil Openings
(Note D)

Non Solder Mask Define Pad



4209202-4/E 07/11

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Refer to IPC7351 for alternate board design.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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